rev F

Low Frequency EMI Reduction IC

Features

- FCC approved method of EMI attenuation
- Provides up to 20 dB of EMI suppression
- Generates a low EMI spread spectrum clock of the input frequency
- Optimized for 10 MHz to 35MHz input frequency range
- Internal loop filter minimizes external components and board space
- 4 selectable spread ranges
- SSON control pin for spread spectrum enable and disable options
- Characterizes to work with ***EMI-Lator***®, EMC simulation program.
- Low cycle-to-cycle jitter
- Wide operating range (3V to 5V)
- 16 mA output drives
- TTL or CMOS compatible outputs
- Low power CMOS design
- Available in 8 pin SOIC and TSSOP

Product Description

The P2010 is a selectable spread spectrum frequency modulator designed specifically for PC peripheral and embedded controller markets. The P2010 reduces electromagnetic interference (EMI) at the clock source which provides system wide reduction of EMI of all clock dependent signals. The P2010 allows significant system cost savings by reducing the number of circuit board layers and shielding that are traditionally required to pass EMI regulations.

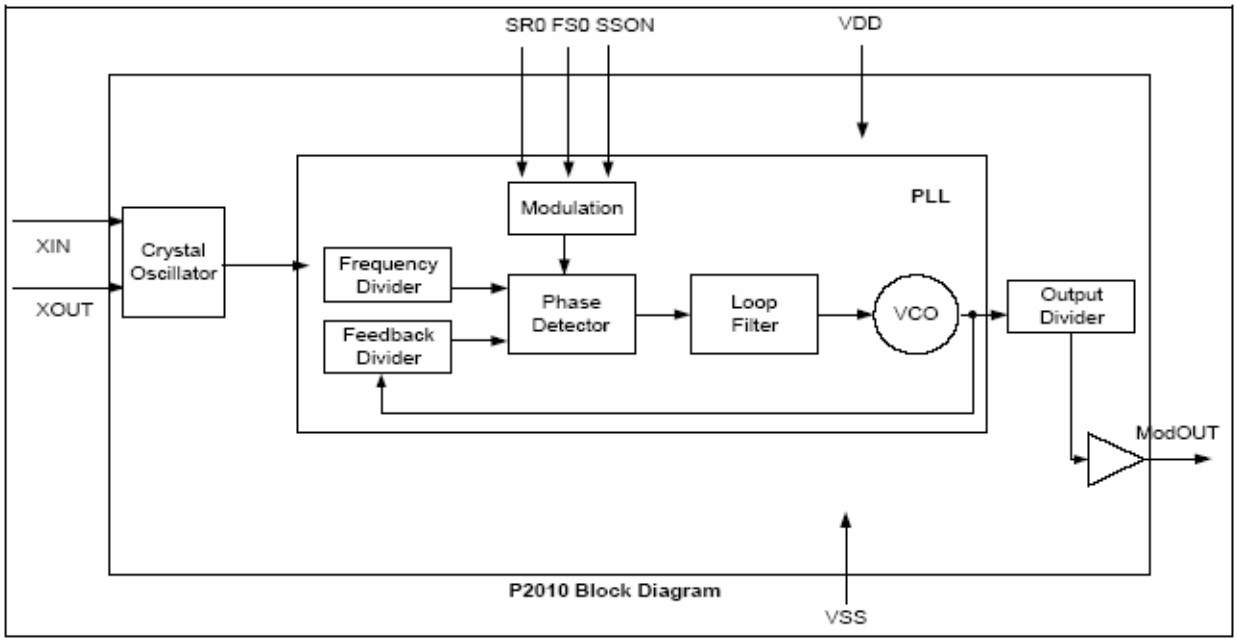
The P2010 uses the most efficient and optimized modulation profile approved by the FCC and is implemented in a proprietary all-digital method.

The P2010 modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock and, more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called "spread spectrum clock generation".

Applications

The P2010 is targeted towards the embedded controller market and PC peripheral markets including scanners, facsimile, MFP's, printers, PDA, IA, and GPS devices.

Block Diagram



P2010 Block Diagram

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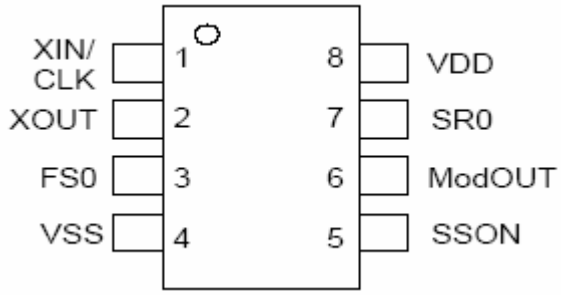
Pin Configuration



Pin Description

Pin#	Pin Name	Type	Description
1	XIN/CLK	I	Connect to crystal or externally generated clock signal.
2	XOUT	I	Connect to crystal. No connect if externally generated clock signal is used.
3	FS0	I	Digital logic input used to select Input Frequency Range (see Table 1). This pin has an internal pull-up resistor.
4	VSS	P	Ground Connection. Connect to system ground.
5	SSON	I	Digital logic input used to enable Spread Spectrum function (Active Low). Spread Spectrum function enable when low. This pin has an internal pull-low resistor.
6	ModOUT	O	Spread Spectrum Clock Output.
7	SR0	I	Digital logic input used to select Spreading Range (see Table 1). This pin has an internal pull-up resistor.
8	VDD	P	Connect to +3.3V or +5.0V

Table 1 - Spread Range Selection

FS0	SR0	Spreading Range	Input Frequency	Modulation rate
1	0	+/- 1.50%	10 MHz to 20 MHz	(Fin/10)*20.83 KHz
1	1	+/- 2.50%	10 MHz to 20 MHz	(Fin/10)*20.83 KHz
0	0	+/- 1.25%	20 MHz to 35 MHz	(Fin/10)*20.83 KHz
0	1	+/- 2.00%	20 MHz to 35 MHz	(Fin/10)*20.83 KHz

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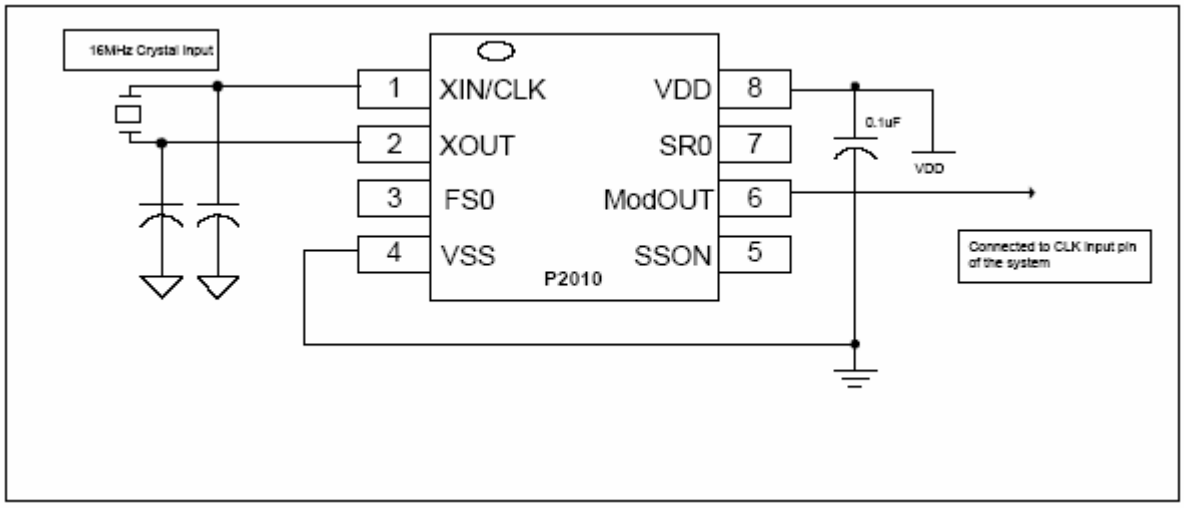
Spread Spectrum Selection
Table 1 illustrates the possible spread spectrum options. The optimal setting should minimize system EMI to the fullest without affecting system performance. The spreading is described as a percentage deviation of the center frequency (Note: the center frequency is the frequency of the external reference input on CLKIN, Pin 1).

Example of a typical printer or scanner application that operates on a clock frequency of 16 MHz:
A spreading selection of FS0=1 and SR0=1 provides a percentage deviation of +/-2.50%* (see Table 1) of F_{cen}. This results in the frequency on ModOUT being swept from 16.40 MHz to 15.60 MHz at a modulation rate of 33.33 KHz (see Table 1). This particular example (see Figure below) given here is a common EMI reduction method for scanner, printer, or embedded applications and has already been adopted by most of the leading manufacturers.

NOTE: Spreading range selection varies from different system manufacturers and their designs.

P2010 Application Schematic for Flat-Bed Scanner



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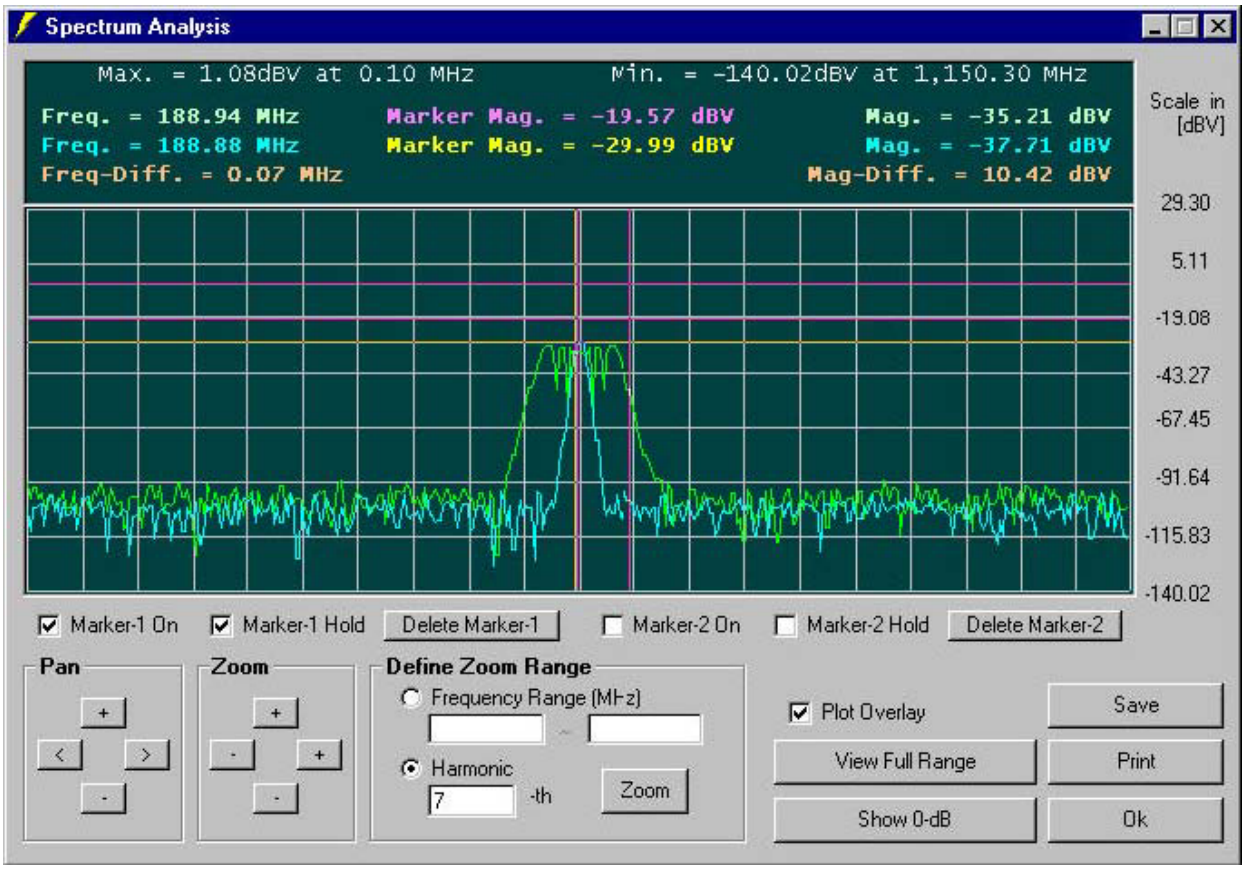
EMC Software Simulation

By using Alliance Semiconductor's proprietary EMC simulation software – EMI-lator®, radiated system level EMI analysis can be made easier to allow a quantitative assessment on Alliance's EMI reduction products. The simulation engine of this EMC software has already been characterized to correlate with the electrical characteristics of Alliance EMI reduction IC's. The figure below is an example of the simulation result. Please visit our web site at www.alsc.comfor information on how to obtain a free copy and demonstration of EMI-lator®.

Simulation Result from EMI-lator®



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Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}, V_{IN}	Voltage on any pin with respect to GND	-0.5 to + 7.0	V
T_{STG}	Storage temperature	-65 to +125	°C
T_A	Operating temperature	0 to +70	°C

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V_{IL}	Input Low Voltage	GND –	-	0.8	V
V_{IH}	Input High Voltage	2.0	-	V_{DD} + 0.3	V
I_{IL}	Input Low Current (pull-up resistor on inputs SR0, 1)	-	-	-35	µA
I_{IH}	Input High Current (pull-down resistor on input SSON)	-	-	35	µA
V_{OL}	Output Low Voltage (V_{DD}=3.3V, I_{OL} = 20 mA)	-	-	0.4	V
V_{OH}	Output High Voltage (V_{DD}=3.3V, I_{OH} = 20 mA)	2.5	-	-	V
I_{DD}	Static Supply Current	-	0.6	-	mA
I_{CC}	Dynamic Supply Current (3.3V and 15pF loading)	4	6	8	mA
V_{DD}	Operating Voltage	2.7	3.3	5.5	V
t_{ON}	Power Up Time (First locked clock cycle after power up)		0.18		ms
Z_{OUT}	Clock Output Impedance		50		Ω

AC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
f_{IN}	Input Frequency when	10	20	30	MHz
t_{LH}*	Output rise time (Measured at 0.8V to 2.0V)	0.7	0.9	1.1	ns
t_{HL}*	Output fall time (Measured at 0.8V to 2.0V)	0.6	0.8	1.0	ns
t_{JC}	Jitter (cycle to cycle)	-	-	360	ps
t_D	Output duty cycle	45	50	55	%
*t_{LH} and t_{HL} are measured into a capacitive load of 15pF					

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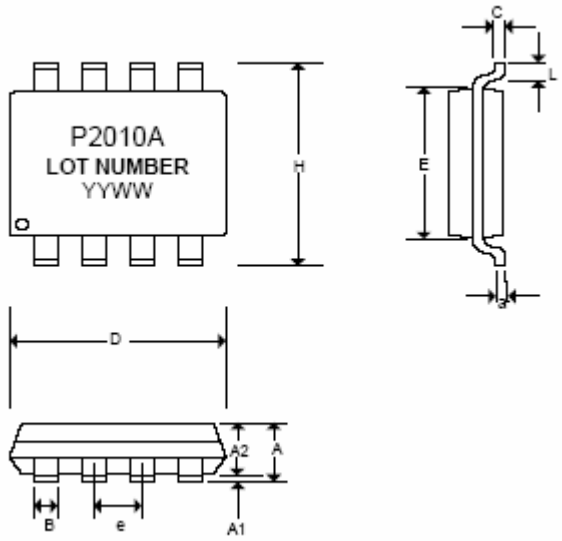
Package Information

Mechanical Package Outline 8-Pin SOIC



Symbol	Dimensions in inches			Dimensions in millimeters		
	Min	Nor	Max	Min	Nor	Max
A	0.057	0.064	0.071	1.45	1.63	1.80
A1	0.004	0.007	0.010	0.10	0.18	0.25
A2	0.053	0.061	0.069	1.35	1.55	1.75
B	0.012	0.016	0.020	0.31	0.41	0.51
C	0.004	0.006	0.01	0.10	0.15	0.25
D	0.186	0.194	0.202	4.72	4.92	5.12
E	0.148	0.156	0.164	3.75	3.95	4.15
e	0.050 BSC			1.27 BSC		
H	0.224	0.236	0.248	5.70	6.00	6.30
L	0.012	0.020	0.028	0.30	0.50	0.70
a	0°	5°	8°	0°	5°	8°

Note: Controlling dimensions are millimeters

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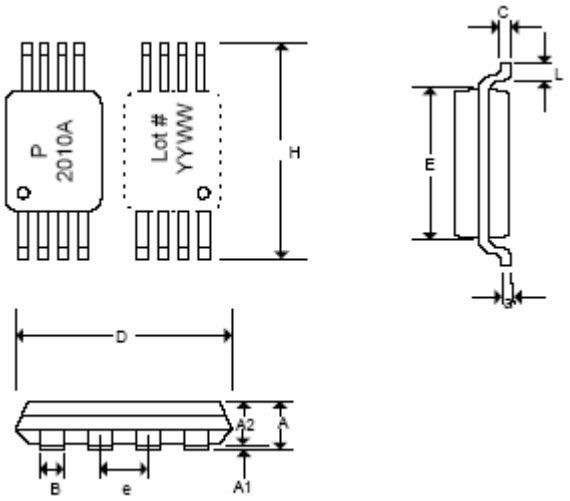
Mechanical Package Outline 8-Pin TSSOP



	Dimensions in inches			Dimensions in millimeters		
Symbol	**Min**	**Nor**	**Max**	**Min**	**Nor**	**Max**
A			0.047			1.10
A1	0.002		0.006	0.05		0.15
A2	0.031	0.039	0.041	0.80	1.00	1.05
B	0.007		0.012	0.19		0.30
C	0.004		0.008	0.09		0.20
D	0.114	0.118	0.122	2.90	3.00	3.10
E	0.169	0.173	0.177	4.30	4.40	4.50
e	0.026 BSC			0.65 BSC		
H	0.244	0.252	0.260	6.20	6.40	6.60
L	0.018	0.024	0.030	0.45	0.60	0.75
a	0°	5°	8°	0°	5°	8°

Note: Controlling dimensions are millimeters

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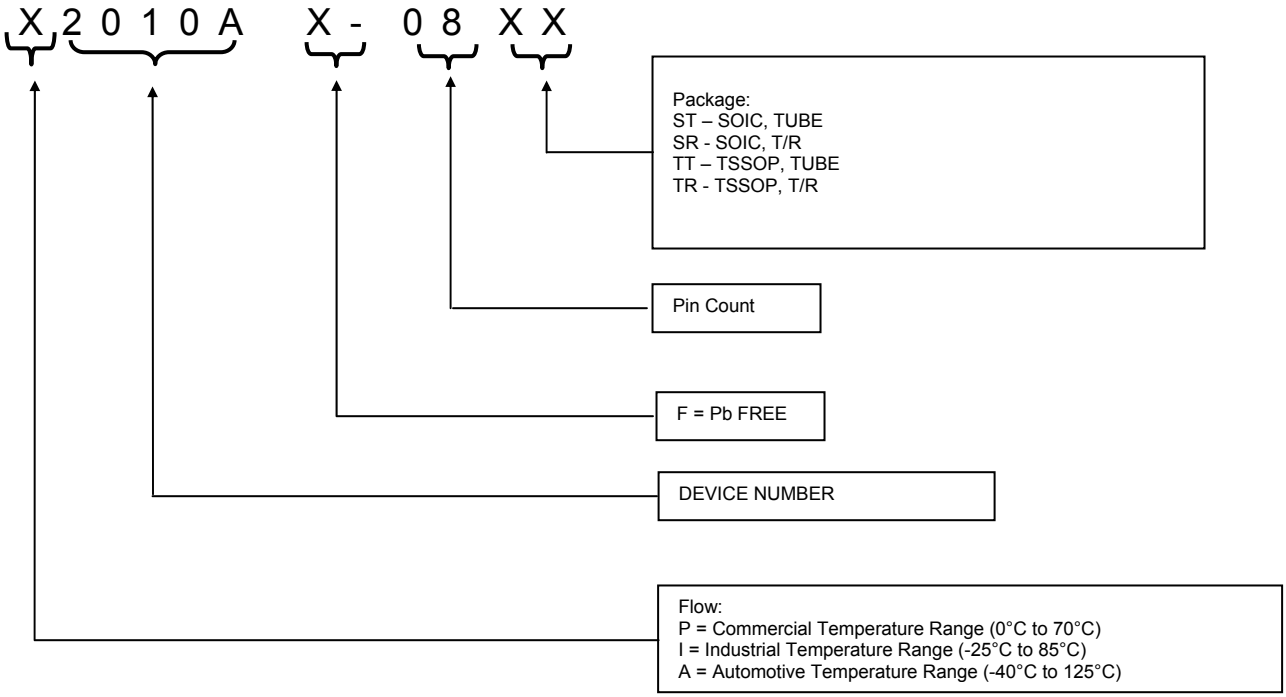
Ordering Codes

Part Number	Marking	Package Type	Qty per reel	Temperature (°C)
P2010A-08ST	P2010A	8 PIN SOIC, TUBE		0 TO 70
P2010A-08SR	P2010A	8 PIN SOIC, TAPE & REEL	2,500	0 TO 70
P2010A-08TT	P2010A	8 PIN TSSOP, TUBE		0 TO 70
P2010A-08TR	P2010A	8 PIN TSSOP, TAPE & REEL	2,500	0 TO 70

Device Ordering Information



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Preliminary datasheet. Specification subject to change without notice.

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